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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, Voltage Detect, WDT
Number of I/O	41
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.5K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21227dfp-u0

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1. Overview

This MCU is built using the high-performance silicon gate CMOS process using the R8C CPU core and is packaged in a 48-pin plastic molded LQFP. This MCU operates using sophisticated instructions featuring a high level of instruction efficiency. With 1 Mbyte of address space, it is capable of executing instructions at high speed. This MCU is equipped with one CAN module and suited to in-vehicle or FA networking.

Furthermore, the data flash (1 KB x 2 blocks) is embedded in the R8C/23 Group.

The difference between R8C/22 and R8C/23 Groups is only the existence of the data flash. Their peripheral functions are the same.

1.1 Applications

Automotive, etc.

1.2 Performance Overview

Table 1.1 outlines the Functions and Specifications for R8C/22 Group and Table 1.2 outlines the Functions and Specifications for R8C/23 Group.

Table 1.1 Functions and Specifications for R8C/22 Group

	Item	Specification
CPU	Number of fundamental instructions	89 instructions
	Minimum instruction execution time	50 ns ($f(XIN) = 20$ MHz, $VCC = 3.0$ to 5.5 V) 100 ns ($f(XIN) = 10$ MHz, $VCC = 2.7$ to 5.5 V)
	Operating mode	Single-chip
	Address space	1 Mbyte
	Memory capacity	Refer to Table 1.3 Product Information for R8C/22 Group
Peripheral Function	Ports	I/O ports: 41 pins, Input port: 3 pins
	Timers	Timer RA: 8 bits x 1 channel, Timer RB: 8 bits x 1 channel (Each timer equipped with 8-bit prescaler) Timer RD: 16 bits x 2 channel (Circuits of input capture and output compare) Timer RE: With compare match function
	Serial interface	1 channel (UART0) Clock synchronous I/O, UART 1 channel (UART1) UART
	Clock synchronous serial interface	1 channel I ² C bus interface ⁽²⁾ , Clock synchronous serial I/O with chip select
	LIN module	Hardware LIN: 1 channel (timer RA, UART0)
	CAN module	1 channel with 2.0B specification: 16 slots
	A/D converter	10-bit A/D converter: 1 circuit, 12 channels
	Watchdog timer	15 bits x 1 channel (with prescaler) Reset start selectable
	Interrupt	Internal: 14 sources, External: 6 sources, Software: 4 sources, Priority level: 7 levels
	Clock generation circuits	2 circuits XIN clock generation circuit (with on-chip feedback resistor) On-chip oscillator (high speed, low speed) High-speed on-chip oscillator has frequency adjustment function.
	Oscillation stop detection function	Stop detection of XIN clock oscillation
	Voltage detection circuit	On-chip
	Power-on reset circuit include	On-chip
Electric Characteristics	Supply voltage	$VCC = 3.0$ to 5.5 V ($f(XIN) = 20$ MHz)(D, J version) $VCC = 3.0$ to 5.5 V ($f(XIN) = 16$ MHz)(K version) $VCC = 2.7$ to 5.5 V ($f(XIN) = 10$ MHz)
	Current consumption	Typ. 12.5 mA ($VCC = 5$ V, $f(XIN) = 20$ MHz, High-speed on-chip oscillator stopping) Typ. 6.0 mA ($VCC = 5$ V, $f(XIN) = 10$ MHz, High-speed on-chip oscillator stopping)
Flash Memory	Programming and erasure voltage	$VCC = 2.7$ to 5.5 V
	Programming and erasure endurance	100 times
Operating Ambient Temperature		-40 to 85°C
		-40 to 125°C (option ⁽¹⁾)
Package		48-pin mold-plastic LQFP

NOTES:

1. When using options, be sure to inquire about the specification.
2. I²C bus is a registered trademark of Koninklijke Philips Electronics N.V.

Table 1.4 Product Information for R8C/23 Group

Current of Aug. 2008

Type No.	ROM Capacity		RAM Capacity	Package Type	Remarks	
	Program ROM	Data Flash				
R5F21236DFP	32 Kbytes	1 Kbyte X 2	2 Kbytes	PLQP0048KB-A	D version	Flash memory version
R5F21237DFP	48 Kbytes	1 Kbyte X 2	2.5 Kbytes	PLQP0048KB-A		
R5F21238DFP	64 Kbytes	1 Kbyte X 2	3 Kbytes	PLQP0048KB-A		
R5F21236JFP	32 Kbytes	1 Kbyte X 2	2 Kbytes	PLQP0048KB-A	J version	
R5F21237JFP	48 Kbytes	1 Kbyte X 2	2.5 Kbytes	PLQP0048KB-A		
R5F21238JFP	64 Kbytes	1 Kbyte X 2	3 Kbytes	PLQP0048KB-A		
R5F2123AJFP	96 Kbytes	1 Kbyte X 2	5 Kbytes	PLQP0048KB-A	K version	
R5F2123CJFP	128 Kbytes ⁽¹⁾	1 Kbyte X 2	6 Kbytes	PLQP0048KB-A		
R5F21236KFP	32 Kbytes	1 Kbyte X 2	2 Kbytes	PLQP0048KB-A		
R5F21237KFP	48 Kbytes	1 Kbyte X 2	2.5 Kbytes	PLQP0048KB-A		
R5F21238KFP	64 Kbytes	1 Kbyte X 2	3 Kbytes	PLQP0048KB-A		
R5F2123AKFP	96 Kbytes	1 Kbyte X 2	5 Kbytes	PLQP0048KB-A		
R5F2123CKFP	128 Kbytes ⁽¹⁾	1 Kbyte X 2	6 Kbytes	PLQP0048KB-A		

NOTE:

- Do not use addresses 20000h to 23FFFh because these areas are used for the emulator debugger. Refer to **24. Notes on Emulator Debugger** of Hardware Manual.

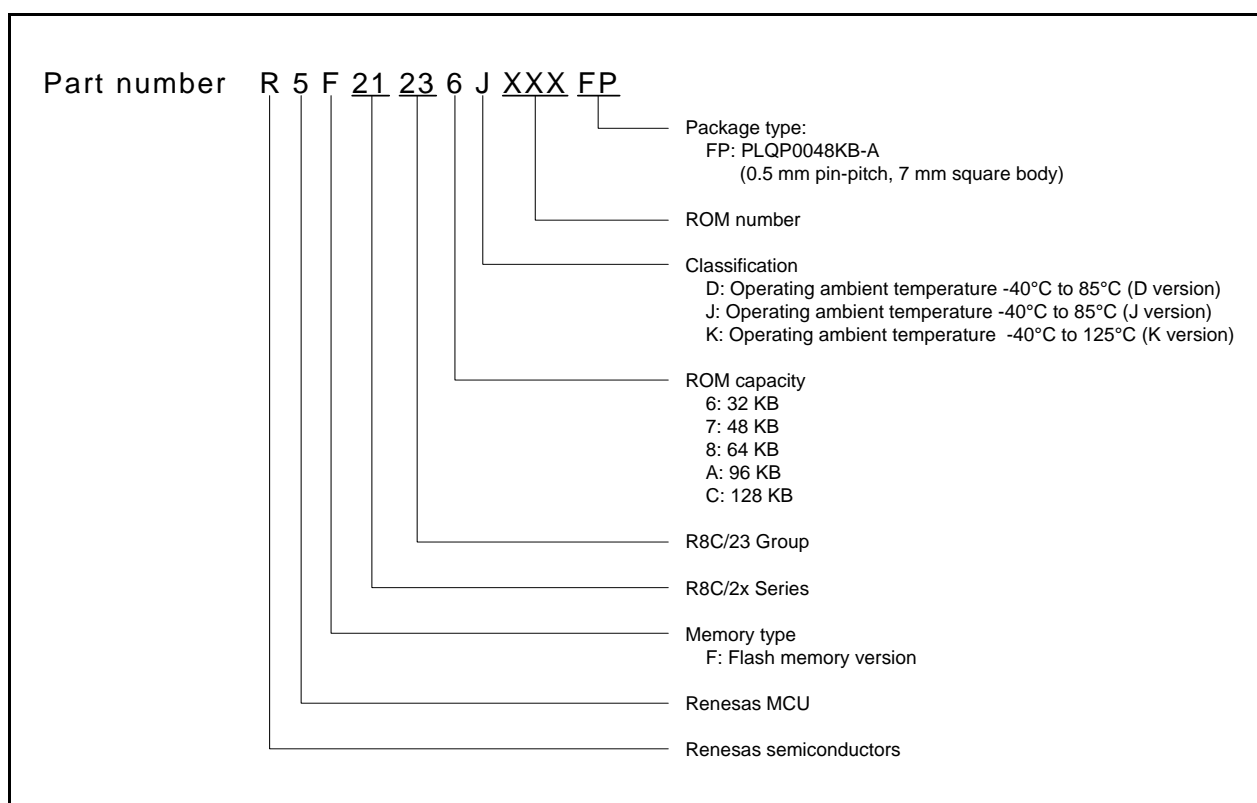


Figure 1.3 Type Number, Memory Size, and Package of R8C/23 Group

1.6 Pin Functions

Table 1.5 lists the Pin Functions and Table 1.6 lists the Pin Name Information by Pin Number.

Table 1.5 Pin Functions

Type	Symbol	I/O Type	Description
Power Supply Input	VCC VSS	I	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog Power Supply Input	AVCC, AVSS	I	Applies the power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset Input	$\overline{\text{RESET}}$	I	Input "L" on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN Clock Input	XIN	I	These pins are provided for the XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
XIN Clock Output	XOUT	O	
$\overline{\text{INT}}$ Interrupt Input	$\overline{\text{INT0}}$ to $\overline{\text{INT3}}$	I	$\overline{\text{INT}}$ interrupt input pins. $\overline{\text{INT0}}$ Timer RD input pins. $\overline{\text{INT1}}$ Timer RA input pins.
Key Input Interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins.
Timer RA	TRAIO	I/O	Timer RA I/O pin.
	TRA0	O	Timer RA output pin.
Timer RB	TRBO	O	Timer RB output pin.
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O ports.
	TRDCLK	I	External clock input pin.
Timer RE	TREO	O	Divided clock output pin.
Serial Interface	CLK0	I/O	Transfer clock I/O pin.
	RXD0, RXD1	I	Serial data input pins.
	TXD0, TXD1	O	Serial data output pins.
I ² C Bus Interface	SCL	I/O	Clock I/O pin.
	SDA	I/O	Data I/O pin.
Clock Synchronous Serial I/O with Chip Select	SSI	I/O	Data I/O pin.
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin.
	SSCK	I/O	Clock I/O pin.
	SSO	I/O	Data I/O pin.
CAN Module	CRX0	I	CAN data input pin.
	CTX0	O	CAN data output pin.
Reference Voltage Input	VREF	I	Reference voltage input pin to A/D converter.
A/D Converter	AN0 to AN11	I	Analog input pins to A/D converter.
I/O Port	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6_0 to P6_7	I/O	CMOS I/O ports. Each port contains an input/output select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by a program.
Input Port	P4_2, P4_6, P4_7	I	Input only ports.

I: Input O: Output I/O: Input and output

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. Of these, R0, R1, R2, R3, A0, A1, and FB comprise a register bank. Two sets of register banks are provided.

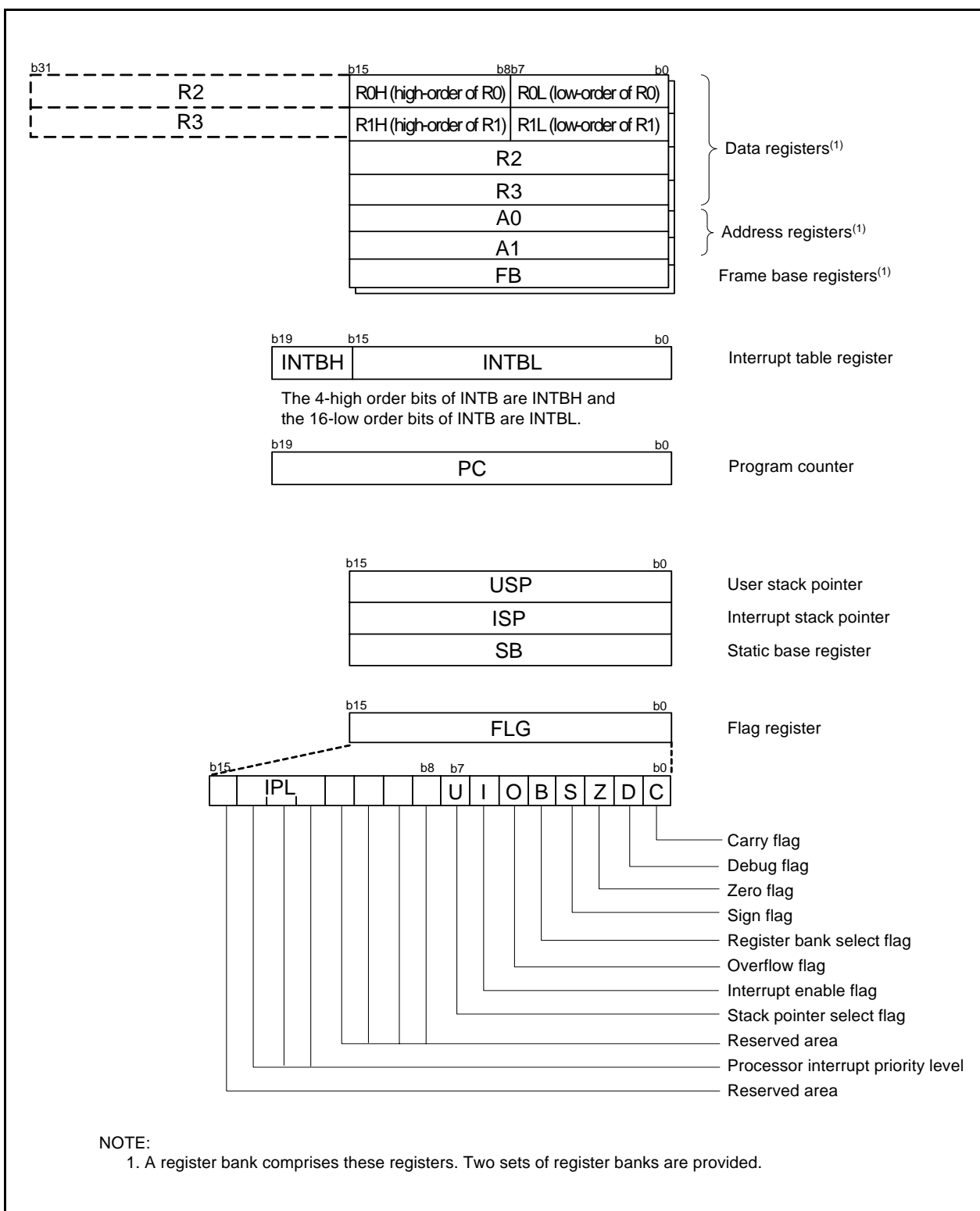


Figure 2.1 CPU Registers

3.2 R8C/23 Group

Figure 3.2 shows a Memory Map of R8C/23 Group. The R8C/23 Group has 1 Mbyte of address space from address 00000h to FFFFFFFh.

The internal ROM (program ROM) is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses 02400h to 02BFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2.5-Kbyte internal RAM is allocated addresses 00400h to 00DFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFR) are allocated addresses 00000h to 002FFh and 01300h to 0147Fh (SFR area for CAN). The peripheral function control registers are allocated them. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

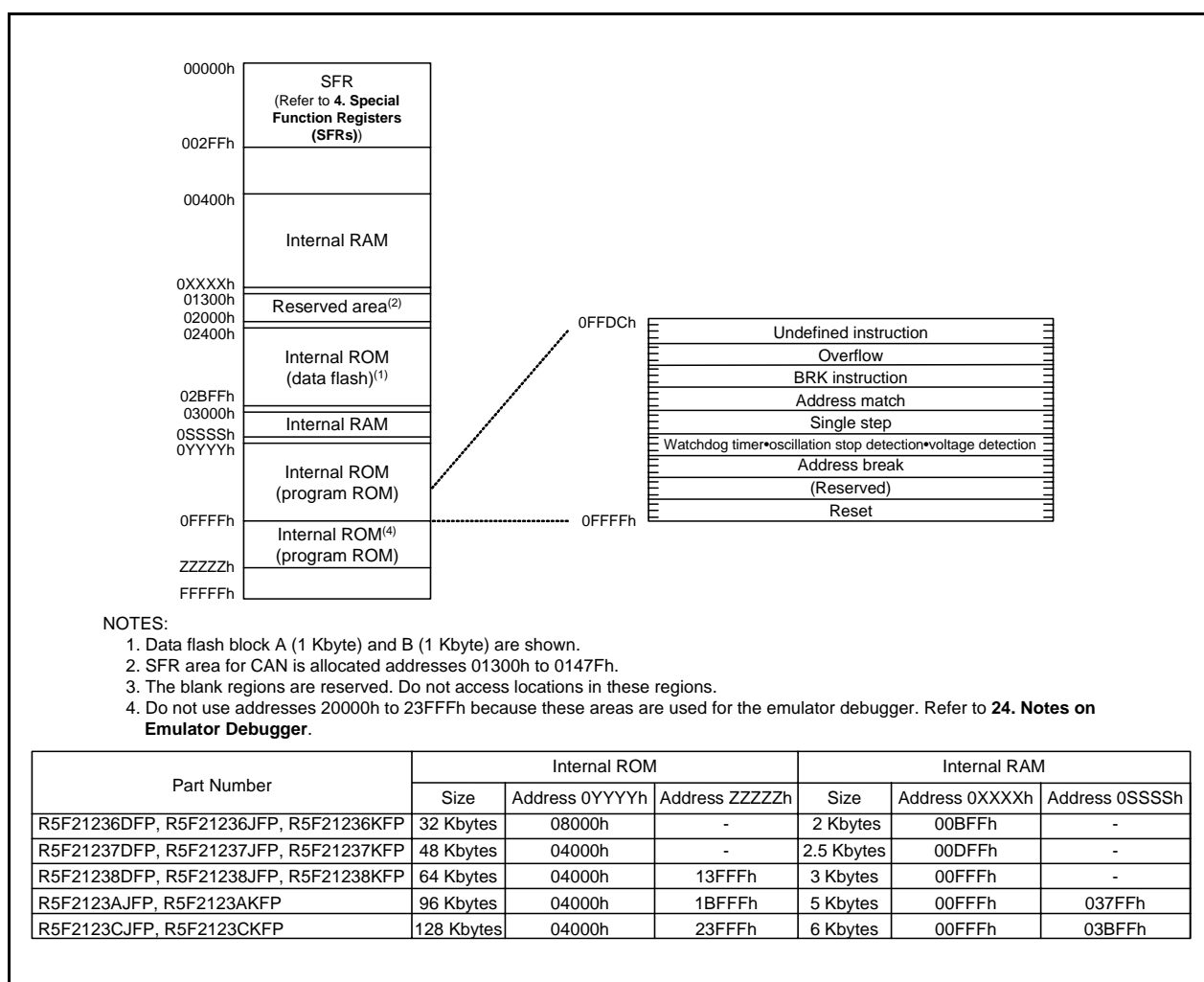


Figure 3.2 Memory Map of R8C/23 Group

Table 4.2 SFR Information (2)⁽¹⁾

Address	Register	Symbol	After reset
0040h			
0041h			
0042h			
0043h	CAN0 Wake Up Interrupt Control Register	C01WKIC	XXXXX000b
0044h	CAN0 Successful Reception Interrupt Control Register	C0RECIC	XXXXX000b
0045h	CAN0 Successful Transmission Interrupt Control Register	C0TRMIC	XXXXX000b
0046h	CAN0 State/Error Interrupt Control Register	C01ERRIC	XXXXX000b
0047h			
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register/IIC Bus Interrupt Control Register ⁽²⁾	SSUIC/IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch			
006Dh			
006Eh			
006Fh			
0070h			
0071h			
0072h			
0073h			
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Selected by the IICSEL bit in the PMR register.

Table 4.6 SFR Information (6)⁽¹⁾

Address	Register	Symbol	After reset
0140h	Timer RD Control Register 0	TRDCR0	00h
0141h	Timer RD I/O Control Register A0	TRDIORA0	10001000b
0142h	Timer RD I/O Control Register C0	TRDIORC0	10001000b
0143h	Timer RD Status Register 0	TRDSR0	11100000b
0144h	Timer RD Interrupt Enable Register 0	TRDIER0	11100000b
0145h	Timer RD PWM Mode Output Level Control Register 0	TRDPOCR0	11111000b
0146h	Timer RD Counter 0	TRD0	00h
0147h			00h
0148h	Timer RD General Register A0	TRDGRA0	FFh
0149h			FFh
014Ah	Timer RD General Register B0	TRDGRB0	FFh
014Bh			FFh
014Ch	Timer RD General Register C0	TRDGRC0	FFh
014Dh			FFh
014Eh	Timer RD General Register D0	TRDGRD0	FFh
014Fh			FFh
0150h	Timer RD Control Register 1	TRDCR1	00h
0151h	Timer RD I/O Control Register A1	TRDIORA1	10001000b
0152h	Timer RD I/O Control Register C1	TRDIORC1	10001000b
0153h	Timer RD Status Register 1	TRDSR1	11000000b
0154h	Timer RD Interrupt Enable Register 1	TRDIER1	11100000b
0155h	Timer RD PWM Mode Output Level Control Register 1	TRDPOCR1	11111000b
0156h	Timer RD Counter 1	TRD1	00h
0157h			00h
0158h	Timer RD General Register A1	TRDGRA1	FFh
0159h			FFh
015Ah	Timer RD General Register B1	TRDGRB1	FFh
015Bh			FFh
015Ch	Timer RD General Register C1	TRDGRC1	FFh
015Dh			FFh
015Eh	Timer RD General Register D1	TRDGRD1	FFh
015Fh			FFh
0160h			
0161h			
0162h			
0163h			
0164h			
0165h			
0166h			
0167h			
0168h			
0169h			
016Ah			
016Bh			
016Ch			
016Dh			
016Eh			
016Fh			
0170h			
0171h			
0172h			
0173h			
0174h			
0175h			
0176h			
0177h			
0178h			
0179h			
017Ah			
017Bh			
017Ch			
017Dh			
017Eh			
017Fh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.8 SFR Information (8)⁽¹⁾

Address	Register	Symbol	After reset
1300h	CAN0 Message Control Register 0	C0MCTL0	00h
1301h	CAN0 Message Control Register 1	C0MCTL1	00h
1302h	CAN0 Message Control Register 2	C0MCTL2	00h
1303h	CAN0 Message Control Register 3	C0MCTL3	00h
1304h	CAN0 Message Control Register 4	C0MCTL4	00h
1305h	CAN0 Message Control Register 5	C0MCTL5	00h
1306h	CAN0 Message Control Register 6	C0MCTL6	00h
1307h	CAN0 Message Control Register 7	C0MCTL7	00h
1308h	CAN0 Message Control Register 8	C0MCTL8	00h
1309h	CAN0 Message Control Register 9	C0MCTL9	00h
130Ah	CAN0 Message Control Register 10	C0MCTL10	00h
130Bh	CAN0 Message Control Register 11	C0MCTL11	00h
130Ch	CAN0 Message Control Register 12	C0MCTL12	00h
130Dh	CAN0 Message Control Register 13	C0MCTL13	00h
130Eh	CAN0 Message Control Register 14	C0MCTL14	00h
130Fh	CAN0 Message Control Register 15	C0MCTL15	00h
1310h	CAN0 Control Register	C0CTLR	X0000001b XX0X0000b
1311h			
1312h	CAN0 Status Register	C0STR	00h X0000001b
1313h			
1314h	CAN0 Slot Status Register	C0SSTR	00h 00h
1315h			
1316h	CAN0 Interrupt Control Register	C0ICR	00h 00h
1317h			
1318h	CAN0 Extended ID Register	C0IDR	00h 00h
1319h			
131Ah	CAN0 Configuration Register	C0CONR	XXh XXh
131Bh			
131Ch	CAN0 Receive Error Count Register	C0RECR	00h
131Dh	CAN0 Transmit Error Count Register	C0TECR	00h
131Eh			
131Fh			
1320h			
1321h			
1322h			
1323h			
1324h			
1325h			
1326h			
1327h			
1328h			
1329h			
132Ah			
132Bh			
132Ch			
132Dh			
132Eh			
132Fh			
1330h			
1331h			
1332h			
1333h			
1334h			
1335h			
1336h			
1337h			
1338h			
1339h			
133Ah			
133Bh			
133Ch			
133Dh			
133Eh			
133Fh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.10 SFR Information (10)⁽¹⁾

Address	Register	Symbol	After reset
1380h	CAN0 Slot 2: Identifier/DLC		XXh
1381h			XXh
1382h			XXh
1383h			XXh
1384h			XXh
1385h			XXh
1386h	CAN0 Slot 2: Data Field		XXh
1387h			XXh
1388h			XXh
1389h			XXh
138Ah			XXh
138Bh			XXh
138Ch			XXh
138Dh			XXh
138Eh	CAN0 Slot 2: Time Stamp		XXh
138Fh			XXh
1390h	CAN0 Slot 3: Identifier/DLC		XXh
1391h			XXh
1392h			XXh
1393h			XXh
1394h			XXh
1395h			XXh
1396h	CAN0 Slot 3: Data Field		XXh
1397h			XXh
1398h			XXh
1399h			XXh
139Ah			XXh
139Bh			XXh
139Ch			XXh
139Dh			XXh
139Eh	CAN0 Slot 3: Time Stamp		XXh
139Fh			XXh
13A0h	CAN0 Slot 4: Identifier/DLC		XXh
13A1h			XXh
13A2h			XXh
13A3h			XXh
13A4h			XXh
13A5h			XXh
13A6h	CAN0 Slot 4: Data Field		XXh
13A7h			XXh
13A8h			XXh
13A9h			XXh
13AAh			XXh
13ABh			XXh
13ACh			XXh
13ADh			XXh
13AEh	CAN0 Slot 4: Time Stamp		XXh
13AFh			XXh
13B0h	CAN0 Slot 5: Identifier/DLC		XXh
13B1h			XXh
13B2h			XXh
13B3h			XXh
13B4h			XXh
13B5h			XXh
13B6h	CAN0 Slot 5: Data Field		XXh
13B7h			XXh
13B8h			XXh
13B9h			XXh
13BAh			XXh
13BBh			XXh
13BCh			XXh
13BDh			XXh
13BEh	CAN0 Slot 5: Time Stamp		XXh
13BFh			XXh

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

Table 4.13 SFR Information (13)⁽¹⁾

Address	Register	Symbol	After reset
1440h	CAN0 Slot 14: Identifier/DLC		XXh
1441h			XXh
1442h			XXh
1443h			XXh
1444h			XXh
1445h			XXh
1446h	CAN0 Slot 14: Data Field		XXh
1447h			XXh
1448h			XXh
1449h			XXh
144Ah			XXh
144Bh			XXh
144Ch			XXh
144Dh			XXh
144Eh	CAN0 Slot 14: Time Stamp		XXh
144Fh			XXh
1450h	CAN0 Slot 15: Identifier/DLC		XXh
1451h			XXh
1452h			XXh
1453h			XXh
1454h			XXh
1455h			XXh
1456h	CAN0 Slot 15: Data Field		XXh
1457h			XXh
1458h			XXh
1459h			XXh
145Ah			XXh
145Bh			XXh
145Ch			XXh
145Dh			XXh
145Eh	CAN0 Slot 15: Time Stamp		XXh
145Fh			XXh
1460h	CAN0 Global Mask Register	C0GMR	XXh
1461h			XXh
1462h			XXh
1463h			XXh
1464h			XXh
1465h			XXh
1466h	CAN0 Local Mask A Register	C0LMAR	XXh
1467h			XXh
1468h			XXh
1469h			XXh
146Ah			XXh
146Bh			XXh
146Ch	CAN0 Local Mask B Register	C0LMBR	XXh
146Dh			XXh
146Eh			XXh
146Fh			XXh
1470h			XXh
1471h			XXh
1472h			
1473h			
1474h			
1475h			
FFFh	Option Function Select Register	OFS	(Note 2)

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a program. Use a flash programmer to write to it.

Table 5.4 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/22 Group	100 ⁽³⁾	–	–	times
		R8C/23 Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
td(SR-SUS)	Time delay from suspend request until erase suspend		–	–	97 + CPU clock × 6 cycle	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3 + CPU clock × 4 cycle	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.7	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. VCC = 2.7 to 5.5 V at Topr = -40 to 85°C (D, J version) / -40 to 125°C (K version), unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 1,000), each block can be erased n times.
For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one. However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure endurance can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If error occurs during block erase, attempt to execute the clear status register command, then the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.8 Power-on Reset Circuit, Voltage Monitor 1 Reset Circuit Electrical Characteristics⁽³⁾

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V_{por1}	Power-on reset valid voltage ⁽⁴⁾		–	–	0.1	V
V_{por2}	Power-on reset or voltage monitor 1 valid voltage		0	–	V_{det1}	V
tr_{th}	External power V_{CC} rise gradient	$V_{CC} \leq 3.6$ V	20 ⁽²⁾	–	–	mV/msec
		$V_{CC} > 3.6$ V	20 ⁽²⁾	–	2,000	mV/msec

NOTES:

1. $T_{opr} = -40^{\circ}\text{C}$ to 85°C (D, J version) / -40°C to 125°C (K version), unless otherwise specified.
2. This condition (the minimum value of external power V_{CC} rise gradient) does not apply if $V_{por2} \geq 1.0$ V.
3. To use the power-on reset function, enable voltage monitor 1 reset by setting the LVD1ON bit in the OFS register to 0, the VW1C0 and VW1C6 bits in the VW1C register to 1 respectively, and the VCA26 bit in the VCA2 register to 1.
4. $tw_{(por1)}$ indicates the duration the external power V_{CC} must be held below the effective voltage (V_{por1}) to enable a power on reset. When turning on the power for the first time, maintain $tw_{(por1)}$ for 30s or more if $-20^{\circ}\text{C} \leq T_{opr} \leq 125^{\circ}\text{C}$, maintain $tw_{(por1)}$ for 3,000s or more if $-40^{\circ}\text{C} \leq T_{opr} < -20^{\circ}\text{C}$.

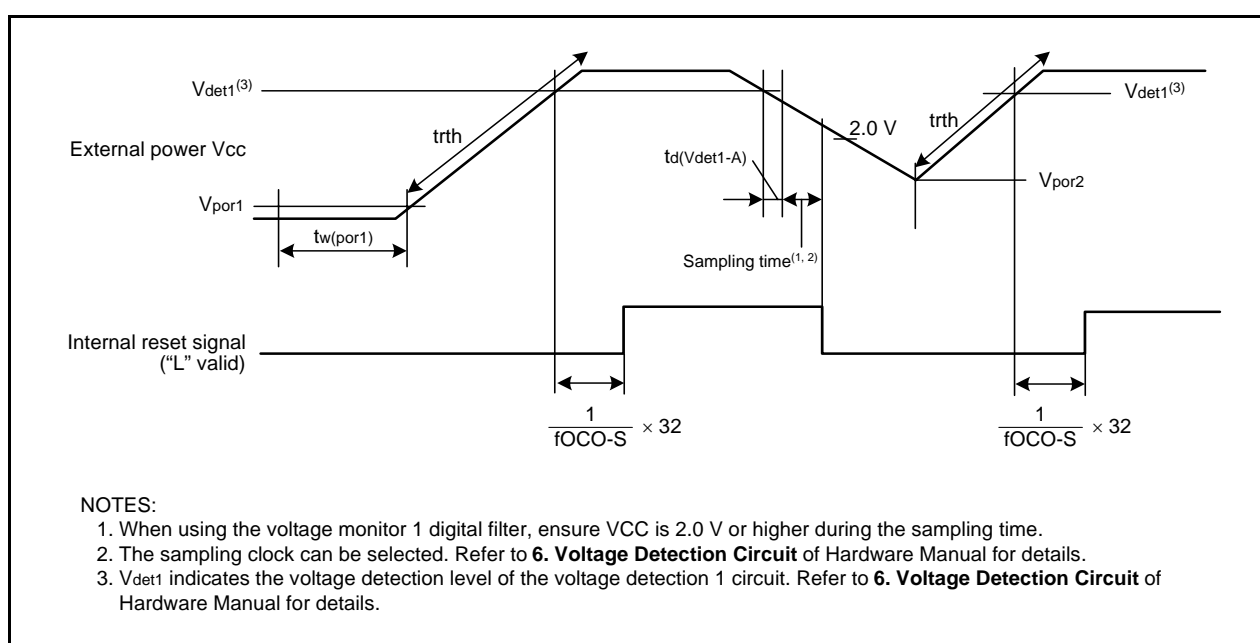
**Figure 5.3 Power-on Reset Circuit Electrical Characteristics**

Table 5.12 Timing Requirements of Clock Synchronous Serial I/O with Chip Select⁽¹⁾

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc ⁽²⁾
tHI	SSCK clock "H" width			0.4	–	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	–	0.6	tsucyc
trISE	SSCK clock rising time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tFALL	SSCK clock falling time	Master		–	–	1	tcyc ⁽²⁾
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
tH	SSO, SSI data input hold time			1	–	–	tcyc ⁽²⁾
tLEAD	SCS setup time	Slave		1tcyc + 50	–	–	ns
tLAG	SCS hold time	Slave		1tcyc + 50	–	–	ns
tOD	SSO, SSI data output delay time			–	–	1	tcyc ⁽²⁾
tSA	SSI slave access time			–	–	1tcyc + 100	ns
tOR	SSI slave out open time			–	–	1tcyc + 100	ns

NOTES:

1. Vcc = 2.7 to 5.5 V, Vss = 0 V at Topr = -40 to 85°C (D, J version) / -40 to 125°C (K version), unless otherwise specified.
2. 1tcyc = 1/f1(s)

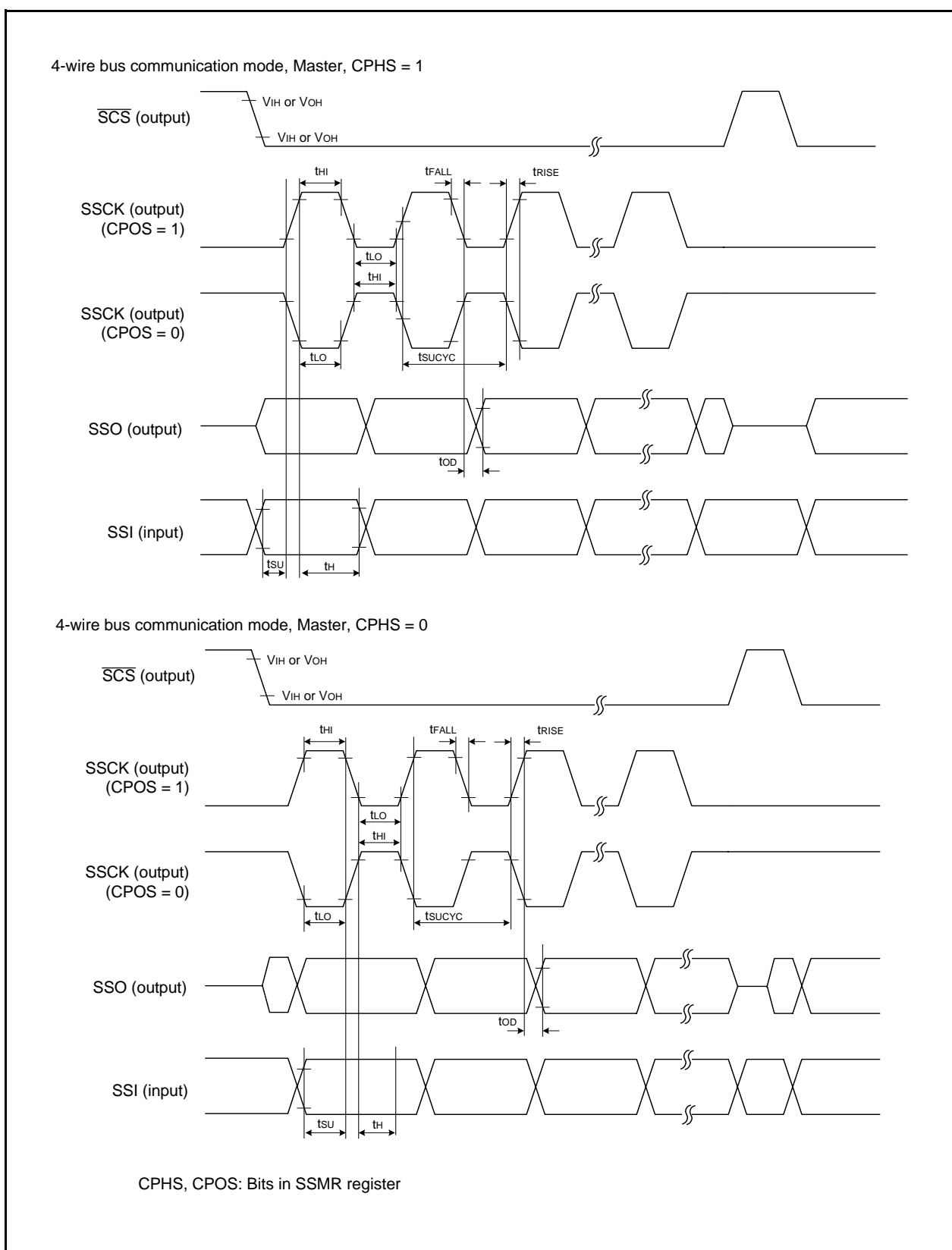


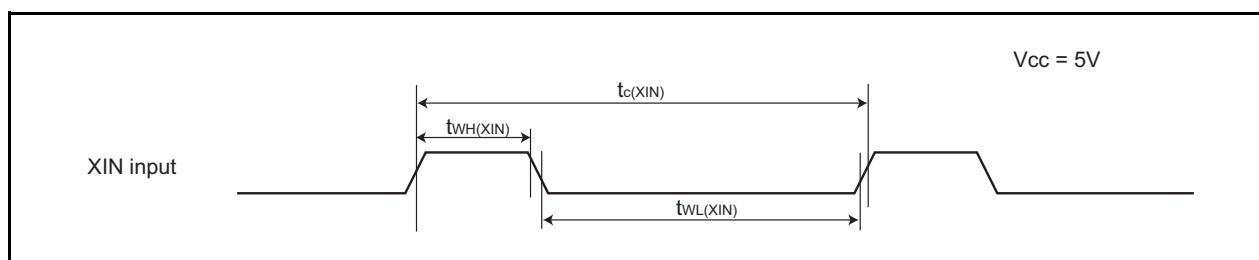
Figure 5.4 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Master)

**Table 5.15 Electrical Characteristics (2) [V_{CC} = 5 V]
(T_{opr} = -40 to 85°C (D, J version) / -40 to 125°C (K version), Unless Otherwise Specified.)**

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) In single-chip mode, the output pins are open and other pins are Vss	High-clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	12.5	25.0	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	10.0	20.0	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	6.5	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	6.5	–	mA
			XIN = 16MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	5.0	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.5	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	6.5	13.0	mA
			XIN clock off High-speed on-chip oscillator on fOCO= 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	3.2	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8 FMR47 = 1	–	150	300	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA20 = 0 VCA26 = VCA27 = 0	–	60	120	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA20 = 0 VCA26 = VCA27 = 0	–	38	76	μA
		Stop mode Topr = 25°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	0.8	3.0	μA
		Stop mode Topr = 85°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	1.2	–	μA
		Stop mode Topr = 125°C	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA26 = VCA27 = 0	–	4.0	–	μA

Timing Requirements (Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^{\circ}\text{C}$) [$V_{CC} = 5\text{ V}$]**Table 5.16 XIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	50	—	ns
$t_{WH(XIN)}$	XIN input "H" width	25	—	ns
$t_{WL(XIN)}$	XIN input "L" width	25	—	ns

**Figure 5.8 XIN Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.17 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	100	—	ns
$t_{WH(TRAIO)}$	TRAIO input "H" width	40	—	ns
$t_{WL(TRAIO)}$	TRAIO input "L" width	40	—	ns

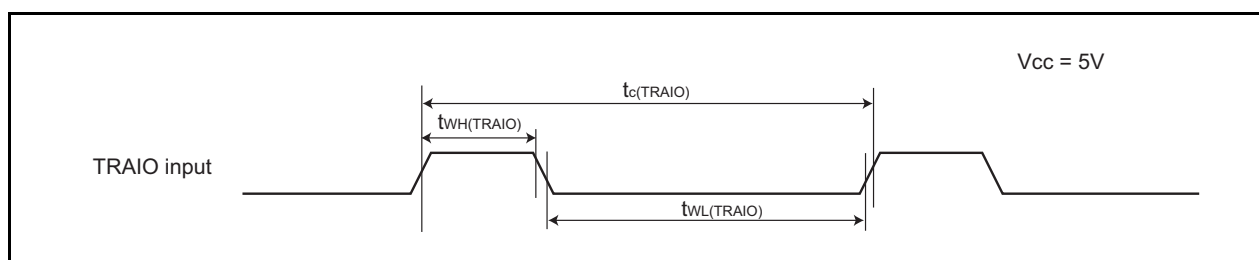
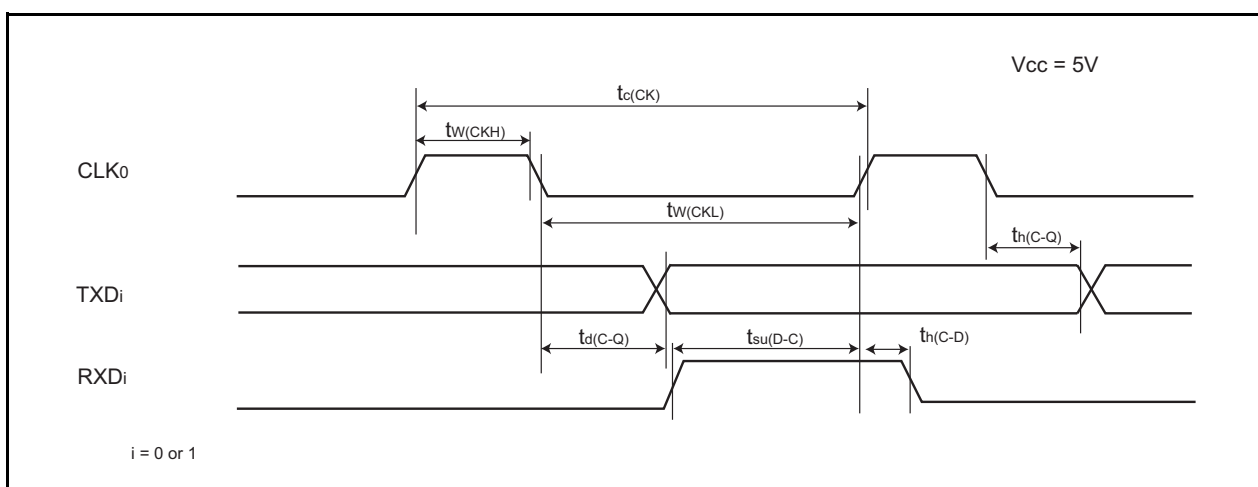
**Figure 5.9 TRAIO Input Timing Diagram when $V_{CC} = 5\text{ V}$**

Table 5.18 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLK0 input cycle time	200	—	ns
$t_{w(CKH)}$	CLK0 input "H" width	100	—	ns
$t_{w(CKL)}$	CLK0 input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

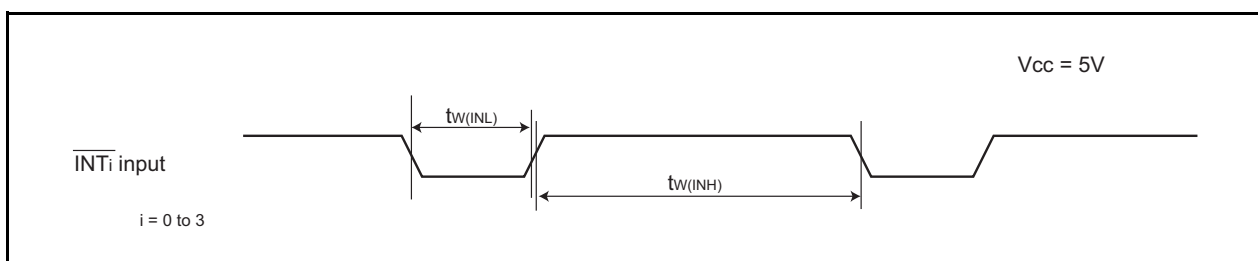
i = 0 or 1

**Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.19 External Interrupt \overline{INTi} (i = 0 to 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	\overline{INTi} input "H" width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	\overline{INTi} input "L" width	250 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the \overline{INTi} input filter select bit, use the \overline{INTi} input HIGH width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the \overline{INTi} input filter select bit, use the \overline{INTi} input LOW width to the greater value, either (1/digital filter clock frequency x 3) or the minimum value of standard.

**Figure 5.11 External Interrupt \overline{INTi} Input Timing Diagram when Vcc = 5 V (i = 0 to 3)**

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